

74AHC541-Q100; 74AHCT541-Q100

Octal buffer/line driver; 3-state

Rev. 1 — 6 June 2013

Product data sheet

1. General description

The 74AHC541-Q100; 74AHCT541-Q100 is a high-speed Si-gate CMOS device.

The 74AHC541-Q100; 74AHCT541-Q100 are octal non-inverting buffer/line drivers with 3-state bus compatible outputs.

The output enable inputs \overline{OE}_0 and \overline{OE}_1 , control the 3-state outputs.

A HIGH on \overline{OE}_n causes the outputs to assume a high-impedance OFF-state.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40°C to $+85^{\circ}\text{C}$ and from -40°C to $+125^{\circ}\text{C}$
- Balanced propagation delays
- All inputs have a Schmitt-trigger action
- Inputs accept voltages higher than V_{CC}
- For 74AHC541-Q100 only: operates with CMOS input levels
- For 74AHCT541-Q100 only: operates with TTL input levels
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200 \text{ pF}$, $R = 0 \Omega$)
- Multiple package options



3. Ordering information

Table 1. Ordering information

Type number	Package		Description	Version
	Temperature range	Name		
74AHC541D-Q100	-40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74AHCT541D-Q100				
74AHC541PW-Q100	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74AHCT541PW-Q100				
74AHC541BQ-Q100	-40 °C to +125 °C	DHVQFN20	plastic dual-in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1
74AHCT541BQ-Q100				

4. Functional diagram

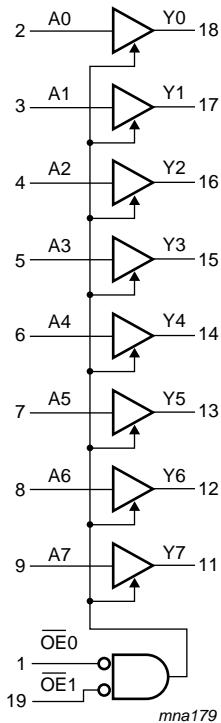


Fig 1. Logic symbol

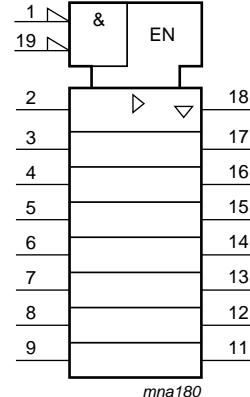


Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning

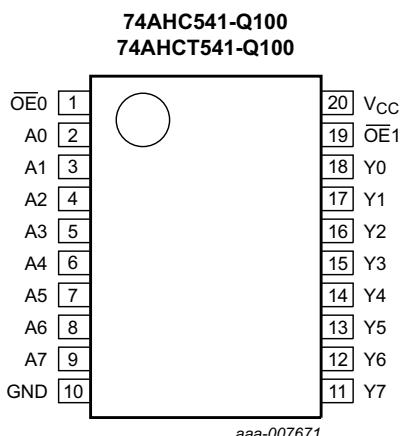


Fig 3. Pin configuration SO20, TSSOP20

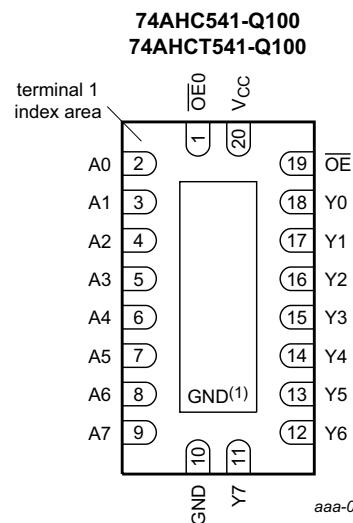


Fig 4. Pin configuration DHVQFN20

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
OE0	1	output enable input (active LOW)
A[0:7]	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
Y[0:7]	18, 17, 16, 15, 14, 13, 12, 11	data output
OE1	19	output enable input (active LOW)
V _{CC}	20	supply voltage

6. Functional description

Table 3. Functional table^[1]

Control		Input	Output
OE0	OE1	An	Yn
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

[1] H = HIGH voltage level;

L = LOW voltage level;

X = don't care;

Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
V_I	input voltage		-0.5	+7.0	V
I_{IK}	input clamping current	$V_I < -0.5$ V	^[1] -20	-	mA
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	^[1] -	± 20	mA
I_O	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5$ V)	-	± 25	mA
I_{CC}	supply current		-	75	mA
I_{GND}	ground current		-75	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C			
	SO20 package		^[2] -	500	mW
	TSSOP20 package		^[3] -	500	mW
	DHVQFN20 package		^[4] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] P_{tot} derates linearly with 8 mW/K above 70 °C.

[3] P_{tot} derates linearly with 5.5 mW/K above 60 °C.

[4] P_{tot} derates linearly with 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74AHC541-Q100			74AHCT541-Q100			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
V _I	input voltage		0	-	5.5	0	-	5.5	V
V _O	output voltage		0	-	V _{CC}	0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 3.3 V ± 0.3 V	-	-	100	-	-	-	ns/V
		V _{CC} = 5.0 V ± 0.5 V	-	-	20	-	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
For type 74AHC541-Q100										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	-	-	1.5	-	1.5	-	V
		V _{CC} = 3.0 V	2.1	-	-	2.1	-	2.1	-	V
		V _{CC} = 5.5 V	3.85	-	-	3.85	-	3.85	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	-	0.5	-	0.5	-	0.5	V
		V _{CC} = 3.0 V	-	-	0.9	-	0.9	-	0.9	V
		V _{CC} = 5.5 V	-	-	1.65	-	1.65	-	1.65	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = −50 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = −50 μA; V _{CC} = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	V
		I _O = −50 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = −4.0 mA; V _{CC} = 3.0 V	2.58	-	-	2.48	-	2.40	-	V
V _{OL}	LOW-level output voltage	I _O = −8.0 mA; V _{CC} = 4.5 V	3.94	-	-	3.8	-	3.70	-	V
		V _I = V _{IH} or V _{IL}								
		I _O = 50 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 50 μA; V _{CC} = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 50 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
I _{OZ}	OFF-state output current	I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I _O = 8.0 mA; V _{CC} = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	4.0	-	40	-	80	μA

Table 6. Static characteristics ...continued

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C_I	input capacitance		-	3.0	10	-	10	-	10	pF
C_O	output capacitance		-	4.0	-	-	-	-	-	pF
For type 74AHCT541-Q100										
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	-	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$								
		$I_O = -50 \mu\text{A}$	4.4	4.5	-	4.4	-	4.4	-	V
V_{OL}	LOW-level output voltage	$I_O = -8.0 \text{ mA}$	3.94	-	-	3.8	-	3.70	-	V
		$I_O = 50 \mu\text{A}$	-	0	0.1	-	0.1	-	0.1	V
I_{OZ}	OFF-state output current	$I_O = 8.0 \text{ mA}$	-	-	0.36	-	0.44	-	0.55	V
		per input pin; $V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 5.5 \text{ V}; I_O = 0 \text{ A}; V_O = V_{CC} \text{ or GND};$ other pins at V_{CC} or GND	-	-	± 0.25	-	± 2.5	-	± 10.0	μA
I_I	input leakage current	$V_I = V_{CC} \text{ or GND}; V_{CC} = 0 \text{ V to } 5.5 \text{ V}$	-	-	0.1	-	1.0	-	2.0	μA
I_{CC}	supply current	$V_I = V_{CC} \text{ or GND}; I_O = 0 \text{ A}; V_{CC} = 5.5 \text{ V}$	-	-	4.0	-	40	-	80	μA
ΔI_{CC}	additional supply current	per input pin; $V_I = V_{CC} - 2.1 \text{ V}; I_O = 0 \text{ A};$ other pins at V_{CC} or GND; $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	1.35	-	1.5	-	1.5	mA
C_I	input capacitance		-	3	10	-	10	-	10	pF
C_O	output capacitance		-	4.0	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V. For test circuit, see [Figure 7](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
For type 74AHC541-Q100										
t_{pd}	propagation delay	An to Y_n ; see Figure 5 [2] $V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$								
		$C_L = 15 \text{ pF}$	-	5.0	7.0	1.0	8.5	1.0	9.0	ns
		$C_L = 50 \text{ pF}$	-	7.0	10.5	1.0	12.0	1.0	13.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$								
		$C_L = 15 \text{ pF}$	-	3.5	5.0	1.0	6.0	1.0	6.5	ns
		$C_L = 50 \text{ pF}$		5.0	7.0	1.0	8.0	1.0	9.0	ns
t_{en}	enable time	\overline{OEn} to Y_n ; see Figure 6 [2] $V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$								
		$C_L = 15 \text{ pF}$	-	5.5	10.5	1.0	11.0	1.0	13.5	ns
		$C_L = 50 \text{ pF}$	-	7.5	14.0	1.0	16.0	1.0	17.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$								
		$C_L = 15 \text{ pF}$	-	3.5	7.2	1.0	8.5	1.0	9.0	ns
		$C_L = 50 \text{ pF}$	-	5.0	9.2	1.0	10.5	1.0	11.5	ns
t_{dis}	disable time	\overline{OEn} to Y_n ; see Figure 6 [2] $V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$								
		$C_L = 15 \text{ pF}$	-	6.0	11.0	1.0	12.0	1.0	14.0	ns
		$C_L = 50 \text{ pF}$	-	9.5	15.4	1.0	17.5	1.0	19.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$								
		$C_L = 15 \text{ pF}$	-	4.5	7.5	1.0	8.0	1.0	9.5	ns
		$C_L = 50 \text{ pF}$	-	6.5	8.8	1.0	10.0	1.0	11.0	ns
C_{PD}	power dissipation capacitance	$C_L = 50 \text{ pF}; f_i = 1 \text{ MHz}; V_I = \text{GND to } V_{CC}$	[3]	-	10	-	-	-	-	pF

Table 7. Dynamic characteristics ...continued
 GND = 0 V. For test circuit, see [Figure 7](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
For type 74AHCT541-Q100										
t_{pd}	propagation delay	An to Y_n ; see Figure 5 $V_{CC} = 4.5$ V to 5.5 V	[2]							
		$C_L = 15$ pF	-	3.5	5.5	1.0	6.5	1.0	7.0	ns
		$C_L = 50$ pF	-	5.0	8.5	1.0	9.5	1.0	11.0	ns
t_{en}	enable time	\overline{OEn} to Y_n ; see Figure 6 $V_{CC} = 4.5$ V to 5.5 V	[2]							
		$C_L = 15$ pF	-	4.0	7.0	1.0	8.0	1.0	9.0	ns
		$C_L = 50$ pF	-	5.5	10.0	1.0	12.0	1.0	12.5	ns
t_{dis}	disable time	\overline{OEn} to Y_n ; see Figure 6 $V_{CC} = 4.5$ V to 5.5 V	[2]							
		$C_L = 15$ pF	-	5.0	7.0	1.0	8.0	1.0	9.0	ns
		$C_L = 50$ pF	-	7.0	10.0	1.0	12.0	1.0	12.5	ns
C_{PD}	power dissipation	per buffer; $C_L = 50$ pF; $f = 1$ MHz; $V_I = GND$ to V_{CC}	[3]	-	12	-	-	-	-	pF
	capacitance									

[1] Typical values are measured at nominal supply voltage ($V_{CC} = 3.3$ V and $V_{CC} = 5.0$ V).

[2] t_{pd} is the same as t_{PLH} and t_{PHL} .

t_{en} is the same as t_{PZL} and t_{PZH} .

t_{dis} is the same as t_{PLZ} and t_{PHZ} .

[3] C_{PD} is used to determine the dynamic power dissipation P_D (μ W).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

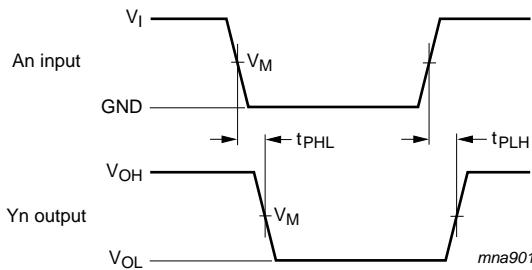
f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts.

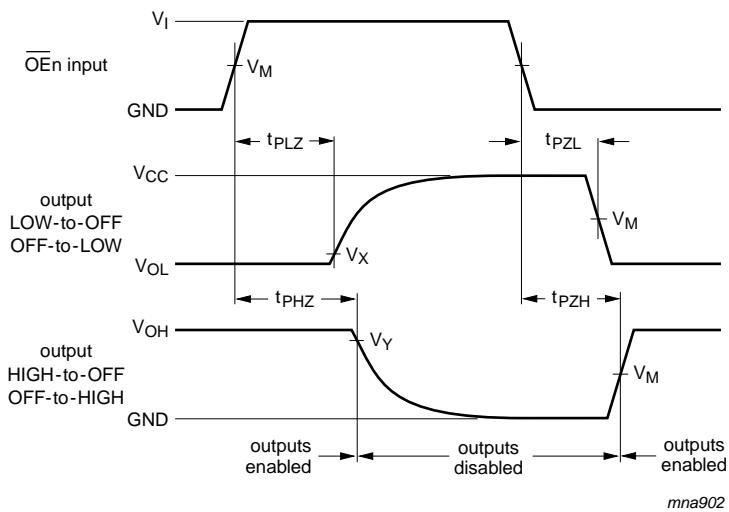
11. Waveforms



Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Propagation delay input (An) to output (Yn)



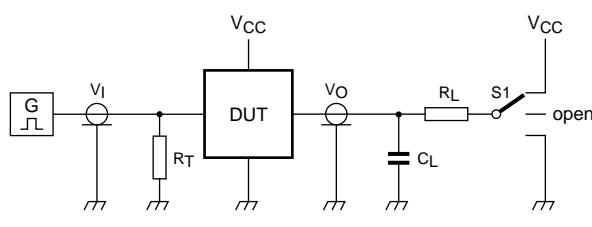
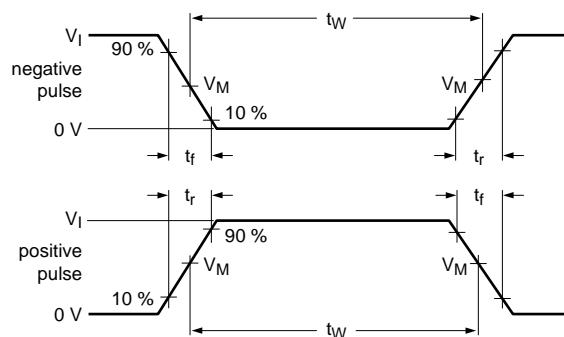
Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Enable and disable times

Table 8. Measurement points

Type	Input	Output		
		V_M	V_M	V_X
74AHC541-Q100	0.5 V_{CC}	0.5 V_{CC}	$V_{OL} + 0.3$ V	$V_{OH} - 0.3$ V
74AHCT541-Q100	1.5 V	0.5 V_{CC}	$V_{OL} + 0.3$ V	$V_{OH} - 0.3$ V



001aad983

Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator

C_L = Load capacitance including jig and probe capacitance

R_L = Load resistor

$S1$ = Test selection switch

Fig 7. Load circuitry for switching times

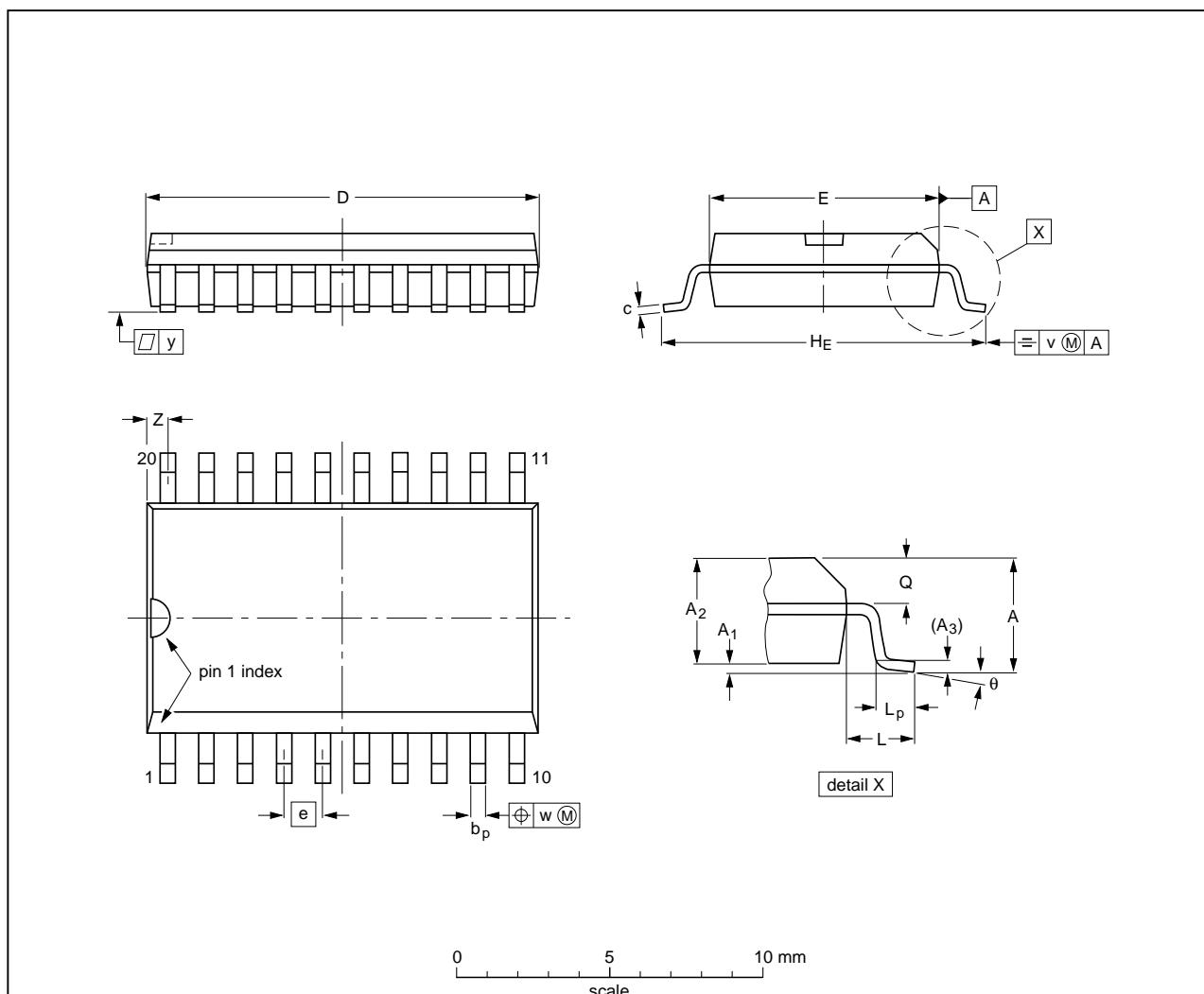
Table 9. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74AHC541-Q100	V_{CC}	3.0 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}
74AHCT541-Q100	3.0 V	3.0 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.65 0.1	0.3 2.25	2.45	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT163-1	075E04	MS-013			09-12-27 03-02-19

Fig 8. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

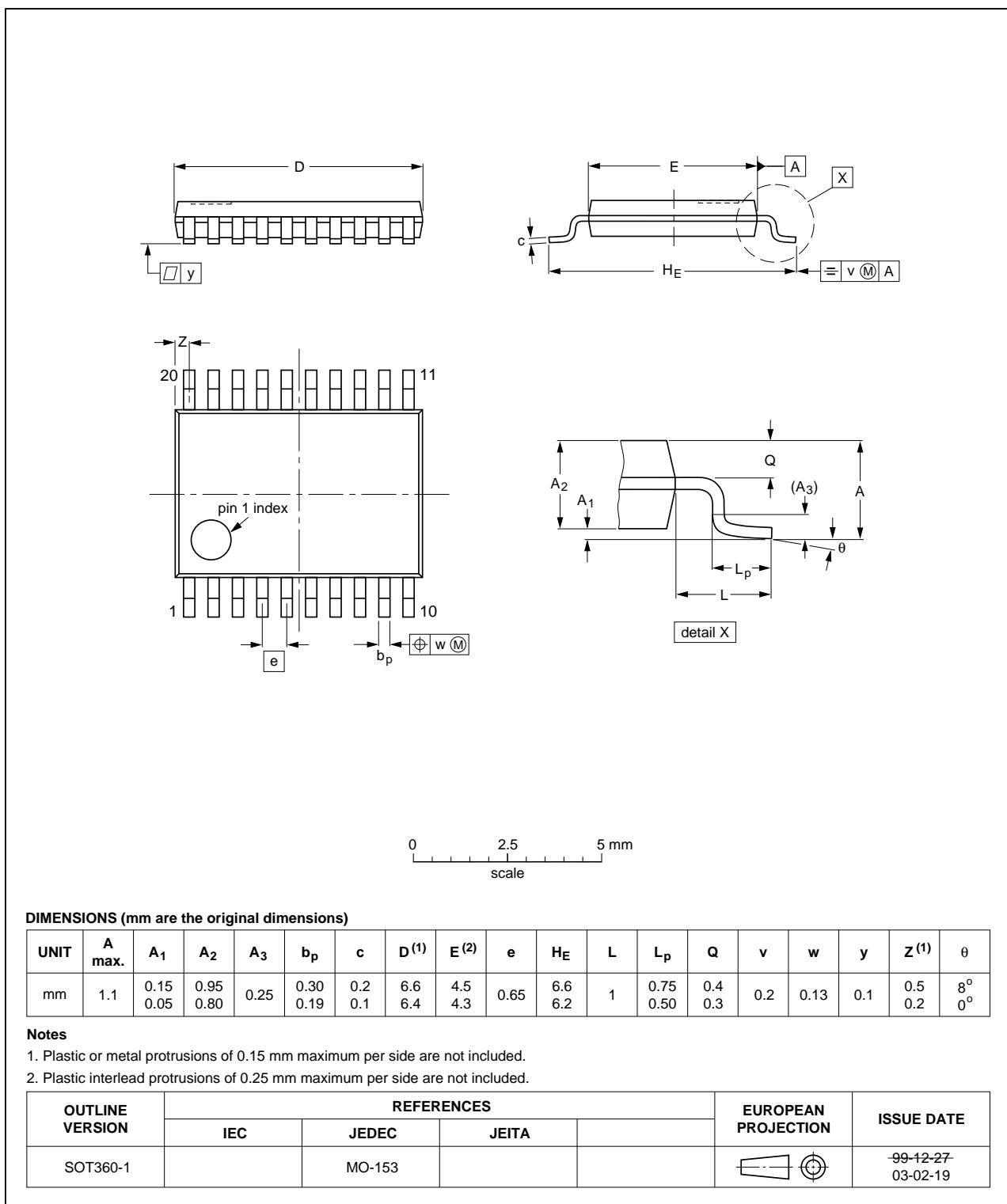


Fig 9. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

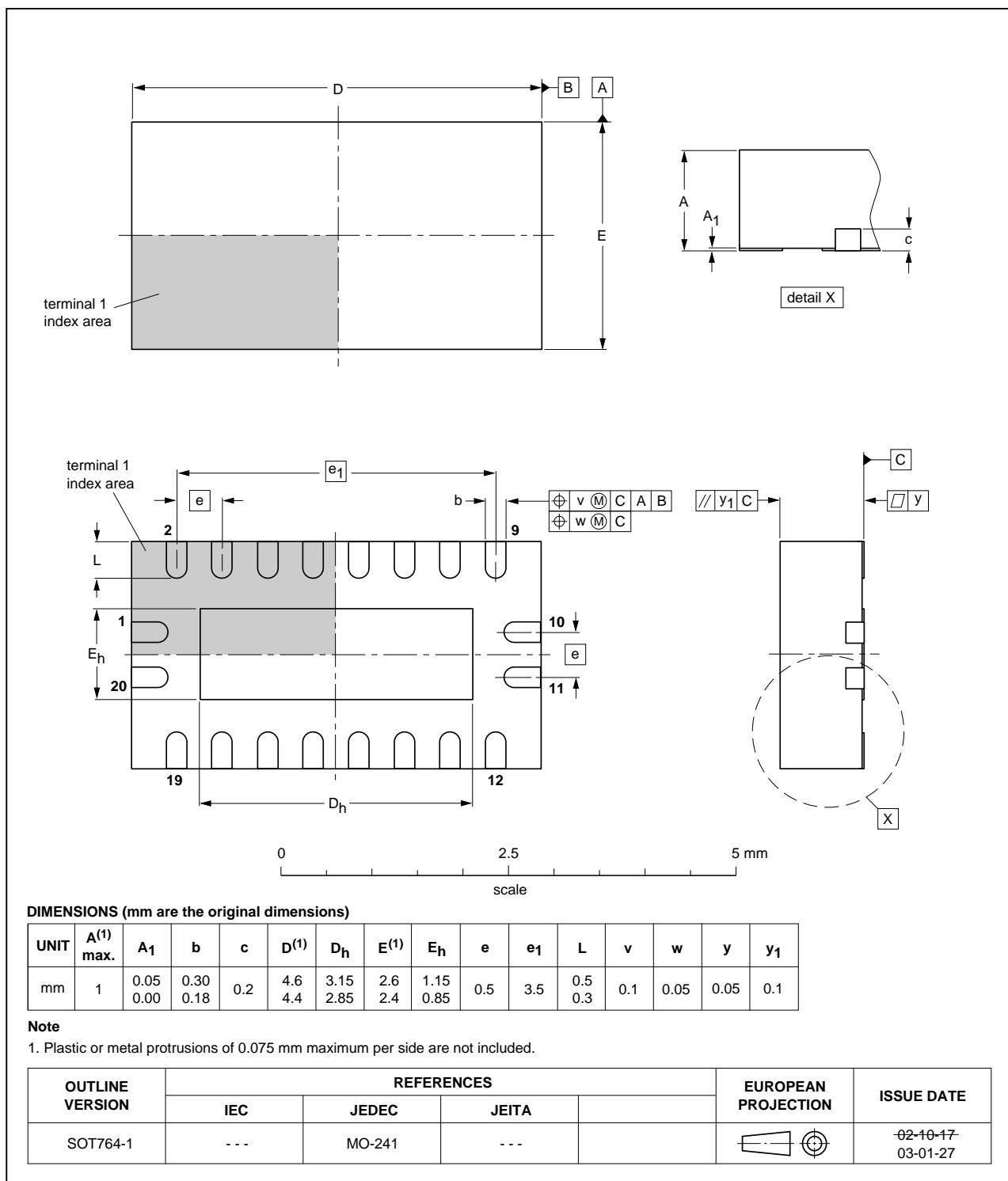


Fig 10. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MIL	Military
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT541_Q100 v.1	20130606	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

15.2 Definitions

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